



**First Semester M.Tech. Degree Examination, Dec.2014/Jan.2015**  
**Digital VLSI Design**

Time: 3 hrs.

Max. Marks:100

**Note: Answer any FIVE full questions.**

1.
  - a. Derive the equations for  $I_{ds}$  for all 3-regions starting from fundamentals. (10 Marks)
  - b. How do you change the above equation to reflect the effect of channel length modulation? (04 Marks)
  - c. Calculate  $I_{ds}$  for nMOS enhancement transistor for following conditions:
    - i)  $V_{ts} = 0.7V$     ii)  $V_{gs} = 2V$   $\lambda = 0$     iii)  $V_{gs} = 2V$ ,  $\lambda = 0.15/V$ . Given:  $\mu_n = 600 \text{ cm}^2/V$ ,  $C_{ox} = 7 \times 10^{-8} \text{ F/cm}^2$ ,  $V_{t0} = 1V$ ,  $V_{DS} = 5V$ ,  $W = 20\mu\text{m}$ ,  $L = 20\mu\text{m}$ . (06 Marks)
2.
  - a. Derive expressions for  $V_{IH}$ ,  $V_{IL}$  and  $V_{th}$  for CMOS inverter. (10 Marks)
  - b. Derive the relation between  $(W/L)_p$  and  $(W/L)_n$  for symmetric CMOS inverter. Also discuss the effect of  $K_R$  variations on VTC. (06 Marks)
  - c. Discuss the enhancement load nMOS inverter. (04 Marks)
3.
  - a. Define propagation delays and derive the expression for  $\tau_{PHL}$  and  $\tau_{PLH}$  for CMOS inverter using differential equation method. (10 Marks)
  - b. Explain 3-stage CMOS ring oscillator. (06 Marks)
  - c. Calculate the total resistance and total capacitance for uniform polysilicon line with length of  $1000\mu\text{m}$  and a width of  $4\mu\text{m}$ . Given: sheet resistance  $30\Omega/\text{square}$ , unit area capacitance  $0.066\text{fF}/\mu\text{m}^2$ , unit length capacitance  $0.046 \text{ fF}/\mu\text{m}$ . (04 Marks)
4.
  - a. What is dynamic CMOS logic? Explain with aid of an example. (06 Marks)
  - b. Illustrate the cascading problem in a dynamic CMOS logic. How is it overcome? (06 Marks)
  - c. Discuss the dynamic voltage bootstrapping circuit with necessary mathematical equations. (08 Marks)
5.
  - a. Discuss the 3-transistor DRAM cell with read and write operations. (10 Marks)
  - b. Explain memory structure SRAM with read and write circuitry with aid of read and write timing diagram. (10 Marks)
6.
  - a. What is short circuit power dissipation? On what parameters does it depend? (10 Marks)
  - b. Describe the types of threshold CMOS circuits used to minimize dynamic power consumption in CMOS digital ICs. (10 Marks)
7.
  - a. Differentiate between CMOS and BiCMOS. (05 Marks)
  - b. Explain the static characteristics of resistive load BJT inverter. (07 Marks)
  - c. Draw the BiCMOS circuits for the following with nMOS transistor for removing the base charge of bipolar transistor. i)  $y = \overline{A}$     ii)  $y = \overline{A + B}$     iii)  $y = \overline{A \cdot B}$ . (08 Marks)
8.
  - a. What is the latch-up problem that arises in bulk CMOS technology? (08 Marks)
  - b. Give any 5 guide lines for avoiding latch-up. (05 Marks)
  - c. With aid of diagram explain the performance modeling procedure. (07 Marks)